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Enhanced contact properties of MoTe₂-FET via laser-induced heavy doping

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Doping technique is vital for applying two-dimensional (2D) materials such as transition metal dichalcogenide (TMDC)-based field effect transistors (FETs), which can control the channel polarity and improve the performance. However, as conventional doping techniques for silicon-based FET are not suitable for 2D materials, the realization of heavy doping of TMDC materials is challenging, especially for n-type heavy doping. This study reports a simple, regioselective, controllable, and chemically stable heavy doping method for 2H-MoTe₂ crystal via high-density laser irradiation. The polarity of the doping can be controlled by changing the irradiation environment. For the MoTe₂-nFET, good performance with enhanced contact properties was obtained using the contact doping method via laser irradiation in a vacuum environment.

1. Introduction

Traditional Si-based metal oxide semiconductor field effect transistors (MOSFETs) contain many dangling-bond-induced traps and exhibit short-channel effects in the post-Moore era, making it more challenging to continue Moore's Law¹). Transition metal dichalcogenide (TMDC) semiconductors, which comprise one transition metal atom and two chalcogen atoms, have an adjustable bandgap of 1-2 eV by selecting the elements and are chemically stable²⁻⁴⁾. A two-dimensional (2D) transistor can effectively prevent the shortchannel effect and it has become the best candidate to replace silicon in next-generation integrated circuits⁵⁾. 2H-MoTe₂ is a member of the TMDC family as a semiconductor with a small band gap of 1.1 eV in monolayer and 0.88 eV in multilayer⁶⁻⁸⁾. Intrinsic 2H-MoTe₂ always shows ambipolar transfer properties due to its small band gap and can be easily doped to exhibit n- or p-type transfer properties 9-12). Therefore, it has excellent potential for applications in complementary MOSFET¹³⁻¹⁵. However, the 2D-FET using TMDC materials still presents a significant challenge in contact properties owing to the Fermi level pinning (FLP) effect in the contact interface caused by intrinsic defects and metal deposition¹⁶⁻²⁰. Therefore, it is difficult to control the channel polarity of the device by selecting a contact metal. Many previous studies have been conducted to improve contact properties. For example, de-pinning interfaces are fabricated by inserting an insulating layer such as monolayer h-BN or Al₂O₃ between metal and 2H-MoTe₂²¹⁻²²⁾. Moreover, using a semi-metallic polymorphic structure such as 1T'-MoTe₂ as an electrode instead of a metal contact with 2H-MoTe₂ and it shows a low contact resistance and ohmic carrier injunction²³⁻ ²⁵⁾. Unlike these methods, contact doping is also an excellent way to decrease contact resistance by reducing the depletion width. However, traditional heavy doping methods, such as ion implantation, are significantly challenging to apply to TMDC materials because of the severe damage caused to the crystal and thermal repairing is not applicable. Chemical doping is a promising method for TMDC materials; however, its doping concentration is usually low²⁶). So far, it has only been used to dope the carrier to change the polarity of the device and improve its performance²⁷⁾. Although there is a report on chemically heavy ntype doping of 2H-MoTe₂ crystal using a benzyl viologen solution, this doping method is not regioselective and unsuitable for large-scale integrated circuits²⁸. Recently, several studies have reported using ozone by UV irradiation to form a WO_x layer having a high work function on the surface of WSe₂, which absorbs electrons from the underlayer and thus heavily dopes the crystalline in p-type by charge transfer mechanizm^{29,30}. However, this method is unstable, and regioselective doping is difficult. In addition, the technique is

suitable only for p-type doping, and whether the WO_x layer participates in the conduction has not been clarified yet. For applying laser irradiation on MoTe₂-FET, it has been reported that weak laser irradiation in an atmosphere environment is a good method for p-type doping³¹⁾. Other studies have used laser irradiation to make the irradiated region undergo a phase transition, which changes the structure from 2H to 1T', and the laser-induced 1T'-MoTe₂ can form good contact with 2H-MoTe₂^{32,33}. However, there have been no reports on the quantitative estimation of the barrier height and the contact resistance by using heavy contact doping via laser irradiation. In this study, a regioselective heavy doping method for 2H-MoTe₂ via high-density laser irradiation was reported. In addition, heavy n- or p-type doping can be achieved by changing the environment in which the sample is placed. Thus, a tunneling-FET (TFET) using MoTe₂ can be realized by laser irradiation in different environmental conditions. Some experimental results on TFET devices fabricated by this technique have been presented at the 2022 International Conference on Solid State Devices and Materials (SSDM 2022)³⁴⁾. Herein, we analyzed the principle of the laser-induced doping in detail and demonstrated that the contact properties of the MoTe₂-nFET were significantly improved via the heavy n-type doping by high-density laser irradiation in a vacuum environment.

2. Experimental methods

The 2H-MoTe₂ bulk crystal was purchased from HQ Graphene, and multilayer 2H-MoTe₂ crystals were exfoliated with a blue tap on a 300 nm SiO₂-coated p^{++} -Si substrate. The thickness of the 2H-MoTe₂ crystals used in this study was about 15 nm. Electrodes were fabricated using electron beam lithography and electron beam metal deposition. 2H-MoTe₂ was placed on the prefabricated electrodes via a dry transfer process for the bottom contact sample. Laser irradiation was performed using a continuous wave laser with a wavelength of 532 nm and output power of 1 W. The laser is guided into a vacuum chamber through an optical microscope. Since a 20× objective lens was used to focus the laser, the laser spot was 4 μ m in diameter on a sample surface. The power of the laser used to irradiate the 2H-MoTe₂ crystal in the chamber was over 100 mW; thus, the optical power density was over 0.8 MW/cm². The time for each laser irradiation was 1 second. Raman spectra were measured using a JASCO RPM-510 Raman Spectrometer with an excitation wavelength of 532 nm installed in an Olympus BX-51 optical microscope. For the contact-doped MoTe₂-nFET, the electrode pattern was first engraved using electron beam lithography. After development, the contact area is irradiated locally with a laser in a vacuum, causing the crystal of the contact

area to be heavily n-type doped. Finally, the metal (Cr/Au) was evaporated onto the contact area. All electrical measurements were performed using a Keithley 2614 B System Source Meter in a vacuum probe station.

3. Results and discussion

3.1 Laser-induced heavy n-doping

Figure 1(a) shows a top-contacted MoTe₂-FET sample after laser irradiation between the electrodes in a vacuum. The laser created a hole in the MoTe₂ crystal at the irradiated region. The diameter of the hole is almost the same as the size of the laser spot. Raman spectroscopy was used to confirm the crystalline structure inside and in the vicinity of the hole. No signal was observed in the hole within the wave-number range, indicating no residue remained after the irradiation of the optical power density of 0.8 MW/cm². Before laser irradiation, the original sample showed two prominent peaks at 170 cm⁻¹ and 230 cm⁻¹, which correspond to the A_{1g} mode and E_{2g} mode of 2H-MoTe₂ as shown in Figure 1(b). After laser irradiation, no significant change was observed in the spectrum at the regions indicated by red-dotted rectangular close to the hole. The color of the remained MoTe₂ crystal did not change after the irradiation as shown in Figure 1(a), indicating that the crystal did not exhibit a layerthinning phenomenon or phase transition caused by the influence of the laser. Figure 1(c) shows the electrical properties of the sample before and after the irradiation. The original sample showed an n-type semiconducting transfer property with an on/off ratio of 10³. After laser irradiation in the channel, the transfer property changed to n⁺-property with a highdrain current (I_d) and almost independent of the gate voltage (V_g) . Figure 1(d) shows the transfer properties of the n⁺-doped sample at different temperatures. The current values in each curve decreased slightly with decreasing the temperature however no significant change was observed in the shape of the curve. This result indicates that the channel region includes a gate-independent degenerately heavily doped region and a gate-dependent lightly doped one in parallel however, even the heavily doped region has a small potential barrier at the contact region.

Generally, MoTe₂ crystals are easily damaged by heat in the atmosphere because of the weak stability of Te atoms. Therefore, increasing the temperature above 400 K began to produce Te vacancies. It is known that such chalcogen-atom vacancies have an effect of n-type doping in TMDC crystals³⁵, and also our first-principal density functional theory (DFT) calculation revealed an appearance of donor level in the band gap close to the conduction band in MoTe₂. Owing to increasing the temperature by the irradiation of the focused laser,

the MoTe₂ crystal absorbed the light because the energy of the green laser was larger than that of the band gap of the multilayer MoTe₂, 0.88 eV^{8} . The temperature of the MoTe₂ crystal during the irradiation can be estimated as above 1200 K³⁶ consequently the crystal was decomposed into Mo and Te atoms and completely sublimated in a vacuum environment as schematically shown in Figure 1(e); therefore, no Raman spectrum was observed in the hole. However, due to the Gaussian profile of the laser, the temperature of MoTe₂ crystal around the hole is also heated up, and then the sublimation of Te atoms creates Te vacancies. Consequently, a heavily n-doped region appears in the vicinity of the hole, and the doping level gradually decays when going away from the hole. Even when the n-doped sample was placed in the atmosphere, no change in the doping level was observed, indicating that this laser-induced heavy n-type doping is stable.

3.2 Laser-induced heavy p-doping

In order to confirm the effect of laser irradiation in the atmosphere, the MoTe₂-FET sample was placed in the Raman spectrometer, and the sample was irradiated linearly with a focused laser of the power density of 0.5 MW/cm^2 by moving the sample stage. Figure 2(a) shows a bottom-contact MoTe₂-FET sample after laser irradiation. A hole (groove) was also created in the crystal however the irradiated region showed an evident color change, which resulted in a thinning behavior. Compared with the case of laser irradiation in a vacuum, there is often a crystal residue in a hole or groove. Raman spectroscopy was used to confirm the crystalline structure in the sample. As shown in Figure 2(b), the directly irradiated area shows a prominent Raman peak at 120 cm⁻¹, which corresponds to the A_{1g} mode of pure Te³⁶⁾. Also, two peaks at 200 cm⁻¹ and 227 cm⁻¹ correspond to the spectra of MoO_2^{37} . Thus, the residuals in the hole (groove) are not layer-thinned MoTe₂ crystal but Te atoms and Mo oxide (MoO₂) after the thermal decomposition caused by the laser irradiation. However, the adjacent area where we focused on showed no significant change in the Raman spectrum from the original one, which corresponds to the 2H-MoTe₂. This indicates that no phase transition occurred in the adjacent area. Figure 2(c) shows the transfer curves of the adjacent area before and after the laser irradiation using the electrodes shown in Figure 2(a). The curve changes from an n-type semiconducting transfer property to a heavily-doped p⁺-type property. This p⁺-type region showed good stability, even in a vacuum and at low temperatures as shown in Figure 2(d). Figure 2(e) shows the schematic diagram in the case of laser irradiation in the atmospheric environment.

The important experimental fact is that the absorption of oxygen molecules at the Te

vacancies for p-type doping needs a heating process; therefore, the n-doped sample prepared by laser irradiation in a vacuum does not change the polarity and the carrier density, even when the sample is exposed to oxygen at room temperature. In addition, it is known that Mo oxide acts as a suitable acceptor for TMDC crystals due to a charge transfer process. The MoO₂ included in the residue inside or around the irradiated region may play a role of an acceptor for the 2H-MoTe₂ in the vicinity of the hole.

3.3 Contact doping for MoTe₂-FET

In MoTe₂-FETs, top-contact using conventional metals usually causes poor contact properties by the FLP effect and severely inhibits the performance. Thus, in this study, the contact doping method via laser irradiation is applied to thin the Schottky barrier caused by the FLP effect and reduce the contact resistance. Figure 3(a) shows a schematic diagram and an optical microscope image of the contact-doped MoTe₂-FET. Metallic source and drain electrodes were contacted with two heavily n-doped regions prepared by laser irradiation in a vacuum before the metal deposition. This sample showed an evident n-type transfer property with a high on/off ratio of 10⁴ at room temperature and 10⁷ at 125 K, as shown in Figure 3(b). The current in the on-state has negligible temperature dependence, indicating no energy barrier exists at high gate voltages. The drain current-drain voltage (I_d - V_d) curves of conventional MoTe₂-FETs usually show a Schottky characteristic in which the device performance is limited in a low-bias region because of the significant energy barrier in the contact interface between the metal and the MoTe2. However, our sample showed good ohmic characteristics at room temperature as seen in Figure 3(c). Moreover, even at 125 K, the sample still showed ohmic features as seen in Figure 3(d), indicating that a suitable contact property was obtained via the contact doping technique by laser irradiation.

However, the temperature dependence of current in the low gate voltage region indicates that a certain level of energy barrier still exists at the contact interface. The Schottky barrier height and contact resistance were estimated using thermionic equations and the Y-function method to prove the excellent contact property further. Equations 1 and 2 describe the thermionic equations for the Schottky barrier height^{38,39}:

$$I_{d} = WA_{2D}^{*}T^{\frac{3}{2}}\exp\left(-\frac{q\phi_{B}}{kT}\right)\left[1 - \exp\left(-\frac{qV_{d}}{kT}\right)\right]$$
(1)
$$A_{2D}^{*} = \frac{q\sqrt{8\pi m^{*}k^{3}}}{h^{2}}$$

$$\phi_B = -\frac{k}{q} \left[\frac{\Delta ln \left(ld / T^2 / 3 \right)}{\Delta T^{-1}} \right]$$
(2)

 where I_d is the drain current, W is the channel width, A_{2D}^* is the modified Richardson constant, k is the Boltzmann constant, q is the electrical charge, m^* is the effective mass, \emptyset_B is the Schottky barrier height, and V_d is the applied drain voltage. Figure 4(a) shows the Schottky barrier height at various gate voltages, where the effective barrier height can be derived from the turning point of the slope of the curve corresponding to the flat band condition, which shows just 6 meV. This indicates that the sample can exhibit good contact properties when the temperature is above 70 K. The Y-function method is applied following Ref. 40. The Y-function is defined as

$$Y = \frac{I_d}{\sqrt{g_m}} = \frac{I_d}{\sqrt{dI_d/dV_g}} \tag{3}$$

where g_m is the transconductance defined by dI_d/dV_g . The threshold voltage (V_T) is extracted through the Y-V_g curve. Then the low-field mobility (μ_0) can be calculated as

$$Y = \left(V_g - V_T\right) \sqrt{\frac{W}{L} C_{ox} \mu_0 V_d} \tag{4}$$

where L is the channel length, C_{ox} is the capacitance of the gate insulator. Next, the mobility attenuation factor (θ) is obtained by using the equation

$$I_d = \frac{W}{L} C_{ox} \left(V_g - V_T \right) \frac{\mu_0}{1 + \theta \left(V_g - V_T \right)} \times V_d \tag{5}$$

Finally, the contact resistance can be calculated from the relation between θ and R_c , namely

$$\theta = \frac{W}{L} \mu_0 C_{ox} R_c \tag{6}$$

For the contact resistance in the on-state ($V_g > 0$) at room temperature, an average value of 56 k $\Omega\mu$ m was obtained, as shown in Figure 4(b). Such a small contact resistance proves that good contact properties have been achieved compared to conventional MoTe₂-FETs. Figure 4(c) shows the temperature dependence of the mobility at $V_g = 40$ V and then the mobility at room temperature is 22 cm²/Vs. If the contact properties are poor, the mobility decreases with decreasing temperature due to the high contact resistance⁴¹. However, the mobility of this sample increases with decreasing temperature, which indicates that the phonon scattering process in the channel is the dominant mechanism in the sample rather than the contact barrier. These experimental results prove that laser irradiation is a suitable method for contact doping to enhance the device performance of the MoTe₂-FET.

4. Conclusions

Heavy n-type and p-type doping of 2H-MoTe₂ crystal was achieved by high-density laser irradiation in a vacuum and an atmosphere environment, respectively. The MoTe₂-nFET showed excellent performance with a negligible Schottky contact barrier of 6 meV and low contact resistance of 56 k $\Omega\mu$ m at room temperature via the contact doping method by laser

Acknowledgments

MoS₂.

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Figure Captions

Fig. 1. (a) Optical microscope image of the sample. (b) Raman spectroscopy of the original crystal and doped crystal. (c) Transfer properties of the MoTe₂-FET before and after laser doping. (d) Temperature dependence of transfer property of heavy n-type doped MoTe₂-FET. (e) Schematic diagram of heavy n-type doping via laser irradiation in a vacuum.

Fig. 2. (a) Optical microscope image of the sample. (b) Raman spectroscopy of the original crystal and doped crystal. (c) Transfer properties of the MoTe₂-FET before and after laser doping. (d) Temperature dependence of transfer property of heavy p-type doped MoTe₂-FET. (e) Schematic diagram of heavy p-type doping via laser irradiation in an atmosphere.

Fig. 3. (a) Schematic diagram and optical microscope image of contact-doped MoTe₂-FET. (b) Transfer curves of contact-doped MoTe₂-FET at different temperatures. *I-V* curves of contact-doped MoTe₂-FET at (c) room temperature and (d) low temperature in V_g varied from -40 to 60 V.

Fig. 4. (a) Schottky barrier height of contact-doped MoTe₂-FET at various gate voltages. (b) Contact resistance which calculated by the Y-function method at various gate voltages. (c) Two terminal mobilities at different temperatures.







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